

ABSTRACT OF THE DISCLOSURE (FIG. 4)

"HEAD SUSPENSION ASSEMBLY"

There is disclosed a head suspension assembly in which a trace having a wiring pattern is disposed on an arm and a suspension. A slider with a magnetic head formed thereon, and a head amplifier IC are mounted on the wiring pattern. An under fill is charged between the head amplifier IC and the wiring pattern, and an outer surface of the head amplifier IC is coated with a resin.